

INTERNATIONAL STANDARD

IEC
60191-6-10

First edition
2003-11

Mechanical standardization of semiconductor devices –

Part 6-10:

**General rules for the preparation of outline drawings of
surface mounted semiconductor device packages –
Dimensions of P-VSON**

Normalisation mécanique des dispositifs à semiconducteurs –

Partie 6-10:

*Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
pour montage en surface –*

Dimensions des boîtiers P-VSON



Reference number
IEC 60191-6-10:2003(E)

Publication numbering

As from 1 January 1997 all IEC publications are issued with a designation in the 60000 series. For example, IEC 34-1 is now referred to as IEC 60034-1.

Consolidated editions

The IEC is now publishing consolidated versions of its publications. For example, edition numbers 1.0, 1.1 and 1.2 refer, respectively, to the base publication, the base publication incorporating amendment 1 and the base publication incorporating amendments 1 and 2.

Further information on IEC publications

The technical content of IEC publications is kept under constant review by the IEC, thus ensuring that the content reflects current technology. Information relating to this publication, including its validity, is available in the IEC Catalogue of publications (see below) in addition to new editions, amendments and corrigenda. Information on the subjects under consideration and work in progress undertaken by the technical committee which has prepared this publication, as well as the list of publications issued, is also available from the following:

- **IEC Web Site (www.iec.ch)**
- **Catalogue of IEC publications**

The on-line catalogue on the IEC web site (www.iec.ch/searchpub) enables you to search by a variety of criteria including text searches, technical committees and date of publication. On-line information is also available on recently issued publications, withdrawn and replaced publications, as well as corrigenda.
- **IEC Just Published**

This summary of recently issued publications (www.iec.ch/online_news/justpub) is also available by email. Please contact the Customer Service Centre (see below) for further information.
- **Customer Service Centre**

If you have any questions regarding this publication or need further assistance, please contact the Customer Service Centre:

Email: custserv@iec.ch
Tel: +41 22 919 02 11
Fax: +41 22 919 03 00

INTERNATIONAL STANDARD

IEC 60191-6-10

First edition
2003-11

Mechanical standardization of semiconductor devices –

Part 6-10:

General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Dimensions of P-VSON

Normalisation mécanique des dispositifs à semiconducteurs –

Partie 6-10:

*Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
pour montage en surface –
Dimensions des boîtiers P-VSON*

© IEC 2003 — Copyright - all rights reserved

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

PRICE CODE

M

For price, see current catalogue

INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES -

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Dimensions of P-VSON

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
6) All users should ensure that they have the latest edition of this publication.
7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60191-6-10 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

Table with 2 columns: FDIS, Report on voting. Row 1: 47D/551/FDIS, 47D565/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

iTeh Standards
(<https://standards.iteh.ai>)
Document Preview

[IEC 60191-6-10:2003](https://standards.iteh.ai/catalog/standards/iec/9935befc-b59c-42a5-b398-8216f71513a9/iec-60191-6-10-2003)

<https://standards.iteh.ai/catalog/standards/iec/9935befc-b59c-42a5-b398-8216f71513a9/iec-60191-6-10-2003>

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Dimensions of P-VSON

1 Scope

This part of IEC 60191 provides the common outline drawings and dimensions for all types of structures and composed materials of plastic very thin small outline non-lead package (hereinafter called P-VSON).

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191(all parts), *Mechanical standardization of semiconductor devices*

ISO/DIS 2692: *Geometrical Product Specification (GPS) – Geometrical tolerancing – Maximum material requirement (MMR) and least material requirement (LMR)*.

3 Terms and definitions

For the purposes of this document, the following definition, as well as those given in other parts of the IEC 60191 series, apply.

3.1 P-VSON

plastic very thin-profile small outline, flat package with no leads

NOTE The package leads (terminals) are on opposite sides of the bottom of the package body and do not extend beyond the package body.